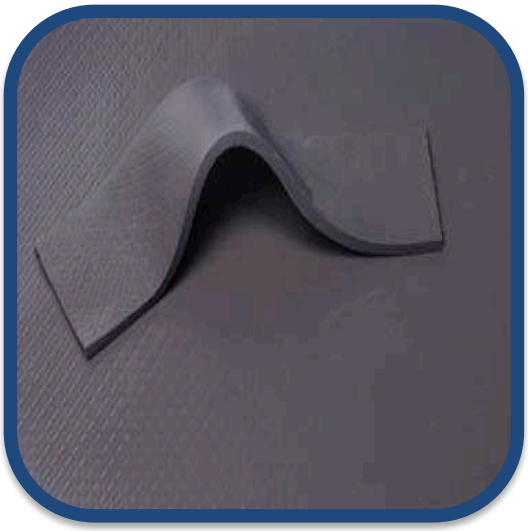
Thermal Gap Pad
EU-TP200



SPECIFIC PRODUCT CHARACTERISTICS:

Features&Benefits	Configurations	Typical application
• Thermal Conductivity: 2.0 W/mK • High conformability • Electrically insulating • Naturally tacky	• Sheet 200x400mm • Custom Die-cut parts • Kiss cut parts on sheet	• Between electronic components such as Semiconductor, IC, CPU.MOS and heatsink. • Led Lighting, LCD TV, Telecom device, wireless Hub,NB, PC, power supply etc • Cooling Module, Thermal module, in all applications where a metal housing is used as heatsink.

CUSTOMIZATIONS:

Die Cutting	Water Jet Cut	Plotter Cut
		

PRODUCT PROPERIES:

Properties	Units	Metric Value	Test Method
Construction & Composition	_	Silicone & Fiberglass	-
Color	_	Dark Gray	Visual
Thickness Range	mm	0,5≈6,0	-
Hardness	Shore C	25	ASTM D2240
Density	g/cc	2,79	ASTM D792
Tensile Strenght	KN/m	0,33	ASTM D412
Elongation	%	78%	ASTM D412
Continuous Use Temp	°C	-40 to 150	EN344
Breakdown Voltage	Kv/mm	≥ 6,0	ASTM D149
Volume Impedance	Ohm-cm	$1,1*10^{16}$	ASTM D257
Dielectric Constant	1MHz	5,75	ASTM D150
Flame Rating	-	V-0	UL94
Thermal Conductivity	W/mK	2,0	ASTM E1461
UL,RoHS, REACH	-	Compliance	-